

DATE: 17th October, 2018

PCN #: 2382

PCN Title: Qualification of Additional Assembly and Test (A/T) site, Conversion to

Palladium Coated Copper Bond Wire with Modified Top Metal

Composition and Thickness, New Lead Frame Type, New Die Attach Material and New Molding Compound for Part Numbers BCP5616QTA

and BCP5616QTC

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request within 30 days as well. Otherwise, samples may not be built prior to this change. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



PRODUCT CHANGE NOTICE

PCN-2382 REV 1

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
17 th October, 2018	17 th January, 2019	Discrete Semiconductors - Automotive	Additional Assembly & Test (A/T) Site / Wafer and Assembly Materials	2382

TITLE

Qualification of Additional Assembly and Test (A/T) site, Conversion to Palladium Coated Copper Bond Wire with Modified Top Metal Composition and Thickness, New Lead Frame Type, New Die Attach Material and New Molding Compound for Part Numbers BCP5616QTA and BCP5616QTC

DESCRIPTION OF CHANGE

This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes is in the process of qualifying "Diodes Technology (Cheng Du) Company Limited" (CAT) located in Chengdu, China as an additional A/T site and also qualifying Palladium Coated Copper (PdCu) bond wire (from Gold bond wire) at CAT for part numbers BCP5616QTA and BCP5616QTC. In order to accommodate the Palladium Coated Copper bond wire, the top metal composition and top metal thickness of the wafer has been modified (with new die name). The lead frame type, die attach material and molding compound type have been changed for better assembly manufacturability at the additional A/T site as well.

The part marking with A/T site identifier for CAT as the additional A/T site will be added in the device data sheet. Please refer to Appendix A for the marking example.

Full electrical characterization and high reliability testing is ongoing and will be completed (*) to ensure there is no change to device functionality or electrical specifications in the datasheet.

(*) Shipment of production material built with new changes at CAT will be gated by the successful completion of qualification.

There will be no change to the Fit or Function of products affected.

IMPACT

There is no change in datasheet parameters and product performance.

PRODUCTS AFFECTED

BCP5616QTA, BCP5616QTC

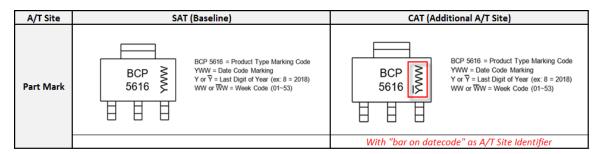
WEB LINKS			
Manufacturer's Notice:	https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/		
For More Information Contact:	http://www.diodes.com/contacts		
Data Sheet:	http://www.diodes.com/products		

DISCLAIMER

Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.



Appendix A: Part Mark Comparison as a result of Additional A/T Site



Rel Date: 2/10/2016